



**IHS NORMALIZED FORMAT  
Material Declaration Data Sheet**

Added  
Normalized

| RoHS Compliant              |                      | YES              |                    | Document Code             |                      | ANDIE00118                             |
|-----------------------------|----------------------|------------------|--------------------|---------------------------|----------------------|--|
| SVHC Presence               |                      | NO               |                    | Material Table Identifier |                      | LQFP 7X7<br>48 (Pb FREE)               |
| PDSL Presence               |                      | NO               |                    | Sub Part                  | Sub Part Weight (mg) | Sub Part Substance Concentration (ppm) |
| Sub Part                    | Sub Part Weight (mg) | Sub Part Details | Sub Part Substance | CAS Number                | Sub Part Weight (mg) | Sub Part Substance Concentration (ppm) |
| MOLD COMPOUND               | 61.848               |                  | EPOXY RESIN        | NOT PROVIDED              | 4.94                 | 79873                                  |
| MOLD COMPOUND               | 61.848               |                  | SILICA,VITREOUS    | 60676-86-0                | 53.2                 | 860173                                 |
| MOLD COMPOUND               | 61.848               |                  | PHENOL RESIN       | NOT PROVIDED              | 3.09                 | 49961                                  |
| MOLD COMPOUND               | 61.848               |                  | ANTIMONY OXIDE     | 1309-64-4                 | 0.247                | 3994                                   |
| MOLD COMPOUND               | 61.848               |                  | BROMINATED RESIN   | NOT PROVIDED              | 0.247                | 3994                                   |
| MOLD COMPOUND               | 61.848               |                  | CARBON BLACK       | 1333-86-4                 | 0.124                | 2005                                   |
| LEAD FRAME                  | 51.2499              |                  | COPPER             | 7440-50-8                 | 49.3                 | 961953                                 |
| LEAD FRAME                  | 51.2499              |                  | NICKEL             | 7440-02-0                 | 1.54                 | 30049                                  |
| LEAD FRAME                  | 51.2499              |                  | SILICON            | 7440-21-3                 | 0.333                | 6498                                   |
| LEAD FRAME                  | 51.2499              |                  | MAGNESIUM          | 7439-95-4                 | 0.0769               | 1500                                   |
| INTERNAL LEAD FRAME PLATING | 0.8                  |                  | SILVER             | 7440-22-4                 | 0.8                  | 1000000                                |
| EXTERNAL LEAD FRAME PLATING | 2.5                  |                  | TIN                | 7440-31-5                 | 2.5                  | 1000000                                |
| BOND WIRE                   | 0.974                |                  | GOLD               | 7440-57-5                 | 0.974                | 1000000                                |



The Source  
for Critical Information and Insight™

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| Sub Part       | Sub Part Weight (mg) | Sub Part Details | Sub Part Substance | CAS Number                | Sub Part Substance Weight (mg) | Sub Part Substance Concentration (ppm) |
| CHIP           | 18.5                 |                  | SILICON            | 7440-21-3                 | 18.5                           | 1000000                                |
| DIE ATTACH     | 1.837                |                  | RESIN              | NOT PROVIDED              | 0.477                          | 259662                                 |
| DIE ATTACH     | 1.837                |                  | SILVER FILLER      | NOT PROVIDED              | 1.36                           | 740338                                 |
|                |                      |                  |                    | Total Weight (mg)         | 137.7089                       |  |